

MA2YD230G

Silicon epitaxial planar type

For high frequency rectification

■ Features

- Forward current (Average) $I_{F(AV)} = 1$ A rectification is possible
- Low forward voltage V_F
- Small reverse current I_R

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	25	V
Repetitive peak reverse voltage	V_{RRM}	25	V
Forward current (Average) *1	$I_{F(AV)}$	1.0	A
Non-repetitive peak forward surge current *2	I_{FSM}	3	A
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

Note) *1: Mounted on an alumina PC board

*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

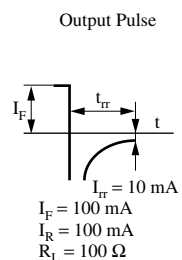
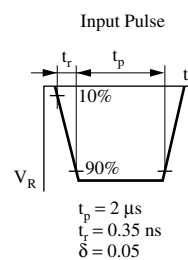
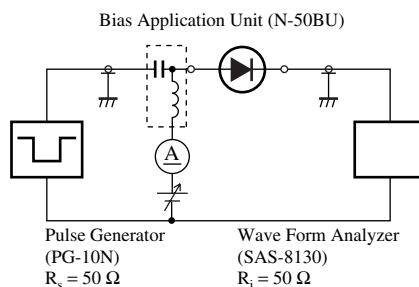
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

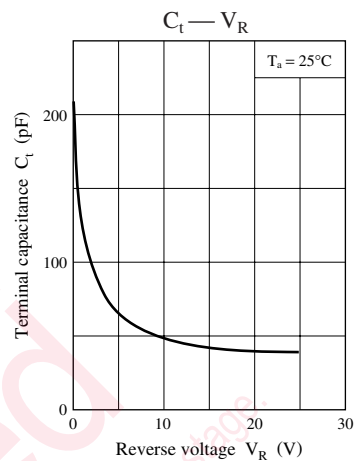
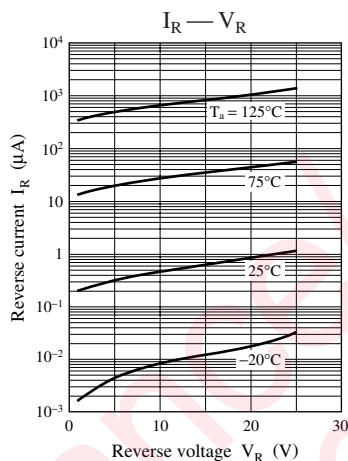
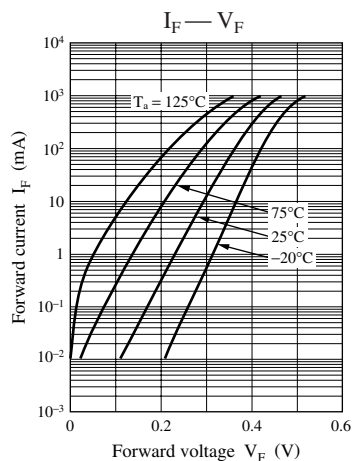
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	$I_F = 0.5$ A		0.42	0.47	V
	V_{F2}	$I_F = 1.0$ A		0.46	0.55	
Reverse current	I_{R1}	$V_R = 15$ V		1.5	20	μA
	I_{R2}	$V_R = 20$ V		2.5	40	
Terminal capacitance	C_t	$V_R = 10$ V, $f = 1$ MHz		45		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 100$ mA $I_{tr} = 10$ mA, $R_L = 100 \Omega$		15		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

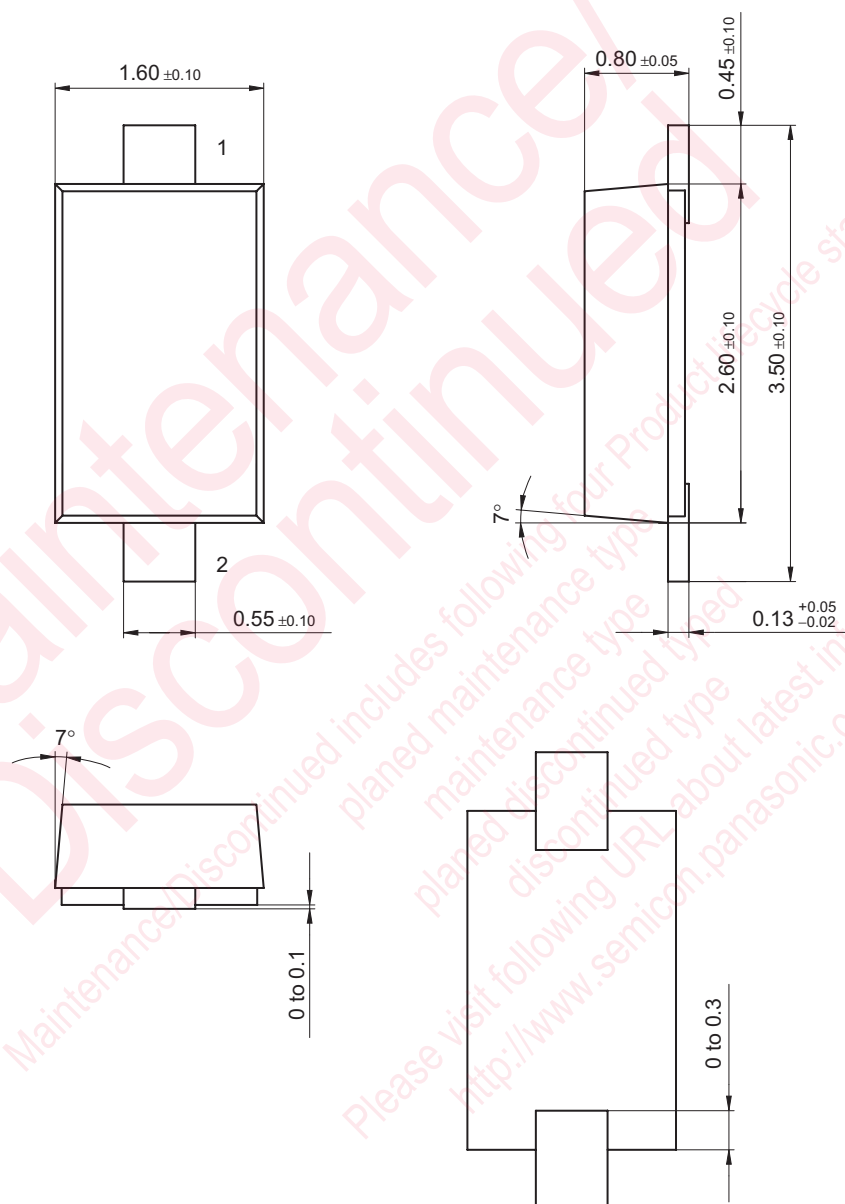
3. *: t_{rr} measurement circuit





Mini2-F2

Unit: mm



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